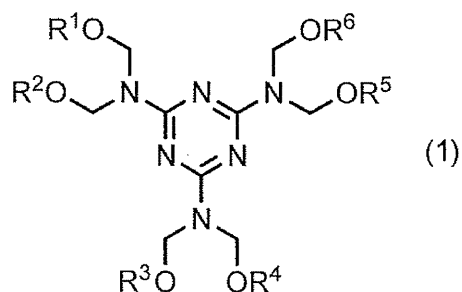
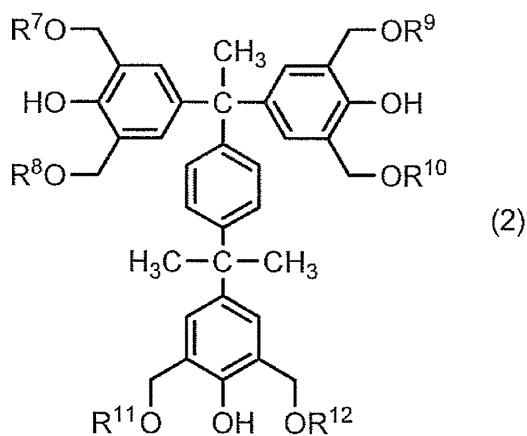


ABSTRACT

Disclosed is a positive-type photosensitive resin composition, comprising an (A) alkali-soluble resin, a (B) compound represented by the following formula (1) or a compound represented by the following formula (2), and a (C) compound having two or more epoxy groups,



wherein R¹ to R⁶ each independently represent an alkyl group having 1 to 10 carbon atoms,



10 wherein R⁷ to R¹² each independently represent an alkyl group having 1 to 10 carbon atoms.